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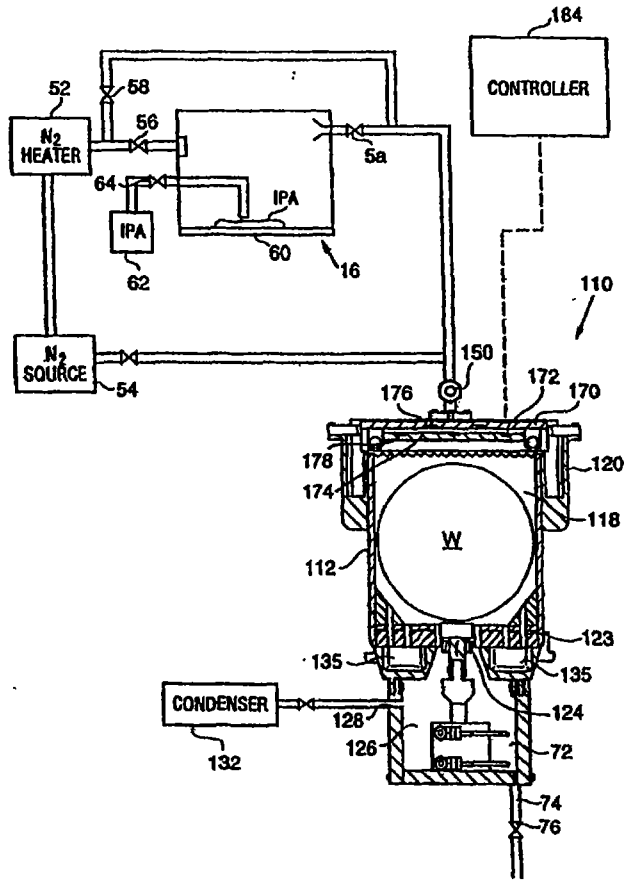
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(54) Title: WAFER CLEANING AND VAPOR DRYING SYSTEM AND METHOD

(57) Abstract

The present invention is a method and system for treating and drying the surface of an object especially a semiconductor wafer. According to the described method, with a wet object positioned in a vessel, a drying vapor of isopropyl alcohol is introduced into the vessel. The drying vapor condenses on the surface of the object and reduces the surface tension of the residual process fluid, causing the residual process fluid to flow off of the surface. Wet processing of the object like HF cleaning and/or deionized water rinsing with subsequent evacuation of process fluid is carried out in the vessel prior to introduction of the drying vapor.



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